AAEON Technology INC.
ISO-9001/ISO-14001 Certified
Industrial Automation PCs

SBC-558P
Thermal Image Analysis Report

Release Date:Dec.27,2002

Issue Stamp	DV Manager	Test Engineer

Thermal Image Analysis

Ⅰ. **Model Name:** **SBC-558P Rev.A0.3 (BIOS:1.0)**

Ⅱ. **Description:** **Half-size CPU Card.**

Ⅲ. **Date:** **Dec. 27, 2002**

Ⅳ. **Measure Site:** **AAEON DV Dept.**

Ⅴ. **Issued by :** **Rex Chang**

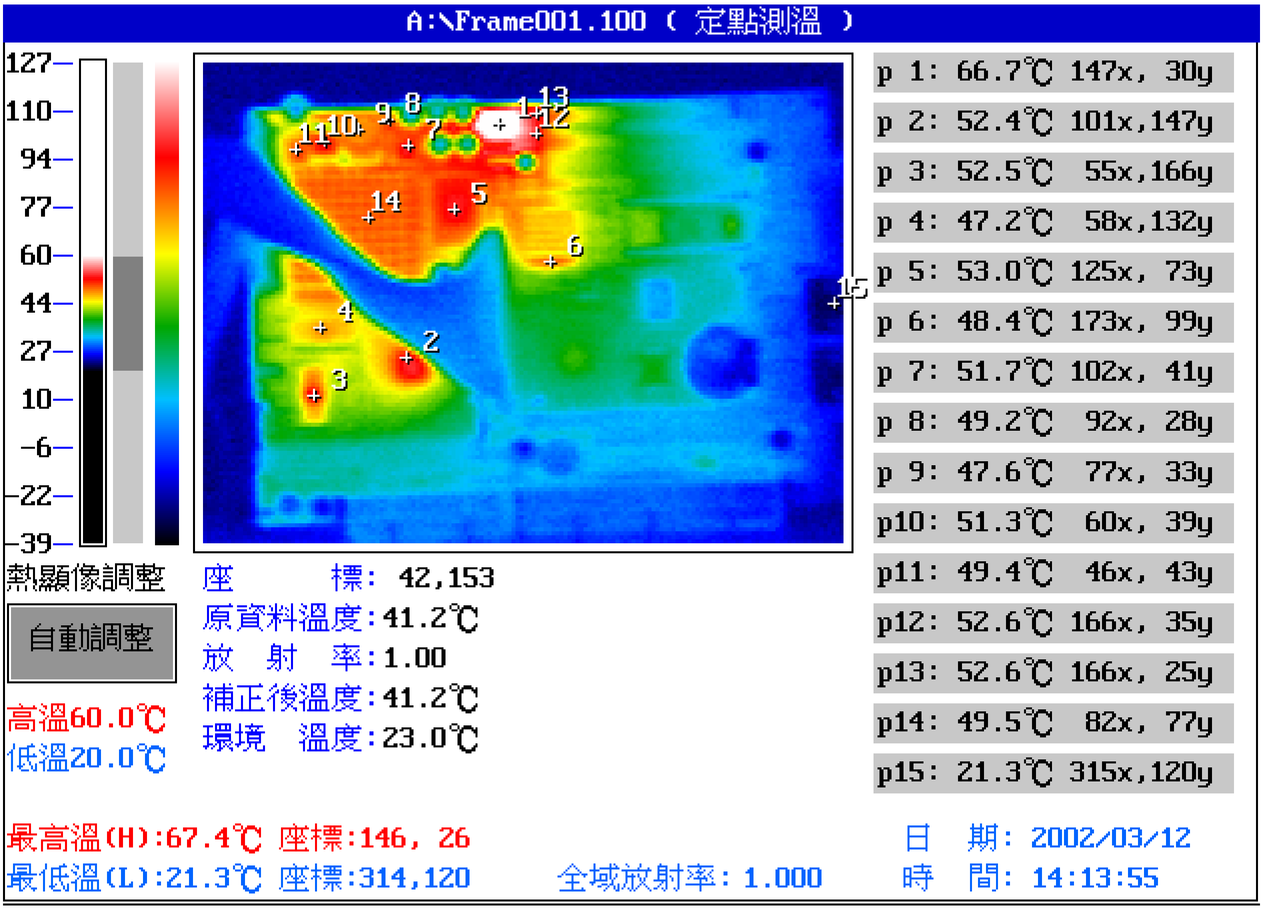
Ⅵ.**Equipment:** **TVS-100 series by NIPPON AVIONICS CO., LTD.**

Ⅶ. **Simulation Environment:**

- **Temperature: 21.3 degrees C**
- **CPU: Onboard Tillamook-MMX 266MHz**
- **RAM: SODRAM 256 MB(SAMSUNG K4S560832B-TC75, PC-133);Only support 128MB**
- **Hardware: Fujitsu MPC3043AP-E 4.3GB**
- **Application Software: BurnIn Test Pro V2.2**
- **Take Picture Time: Power on 30 minutes after**

Temperature Profile Test:

Component Side:



A:\Frame001.100 (定點測溫)

Point	Temperature	Coordinates
p 1:	66.7℃	147x, 30y
p 2:	52.4℃	101x,147y
p 3:	52.5℃	55x,166y
p 4:	47.2℃	58x,132y
p 5:	53.0℃	125x, 73y
p 6:	48.4℃	173x, 99y
p 7:	51.7℃	102x, 41y
p 8:	49.2℃	92x, 28y
p 9:	47.6℃	77x, 33y
p10:	51.3℃	60x, 39y
p11:	49.4℃	46x, 43y
p12:	52.6℃	166x, 35y
p13:	52.6℃	166x, 25y
p14:	49.5℃	82x, 77y
p15:	21.3℃	315x,120y

高溫60.0℃
低溫20.0℃

座 標: 42,153
原資料溫度:41.2℃
放 射 率:1.00
補正後溫度:41.2℃
環境 溫度:23.0℃

最高溫(H):67.4℃ 座標:146, 26
最低溫(L):21.3℃ 座標:314,120
全域放射率: 1.000
日 期: 2002/03/12
時 間: 14:13:55

Point	Position	Describe	Ts	Tm	Note
1	Q1	REG. AMS. AMS1083CM		66.7℃	
2	U17	INTEL.FW82439TX		52.4℃	
3	U20	ICS. ICS9148B-04.		52.5℃	
4	U16	IC SRAM. ELITEMT.LP61L256AS-8		47.2℃	
5	U5	IC. SMD. ELITE. LP61G6464BF-5		53.0℃	
6	U10	IC. SMD. C&T M69000.INTEL		48.4℃	
7	U4	CONV. DC-DC. Semtech. SC1101CS		51.7℃	
8	D1	D Schottky. MICROSEM. SK32B		49.2℃	
9	L3	INDUCTOR. SUMIDA.CDRH-2R4NC		47.6℃	
10	D2	D Schottky. MOMRD1035CTLT4		51.3℃	
11	U3	PWR.MOSFET.VISHAY.Si4420DY-T1		49.4℃	
12	TC3	TCC. 10uF. 25V. 20%. C. SMD		52.6℃	
13	TC1			52.6℃	
14	U9	INTEL CPU. Pentium MMX.266MHz.		49.5℃	
15		The Room Temperature		21.3℃	

1. Operation Temperature (℃):

Ts = Defined by component specification ; Tm = Measured by DV

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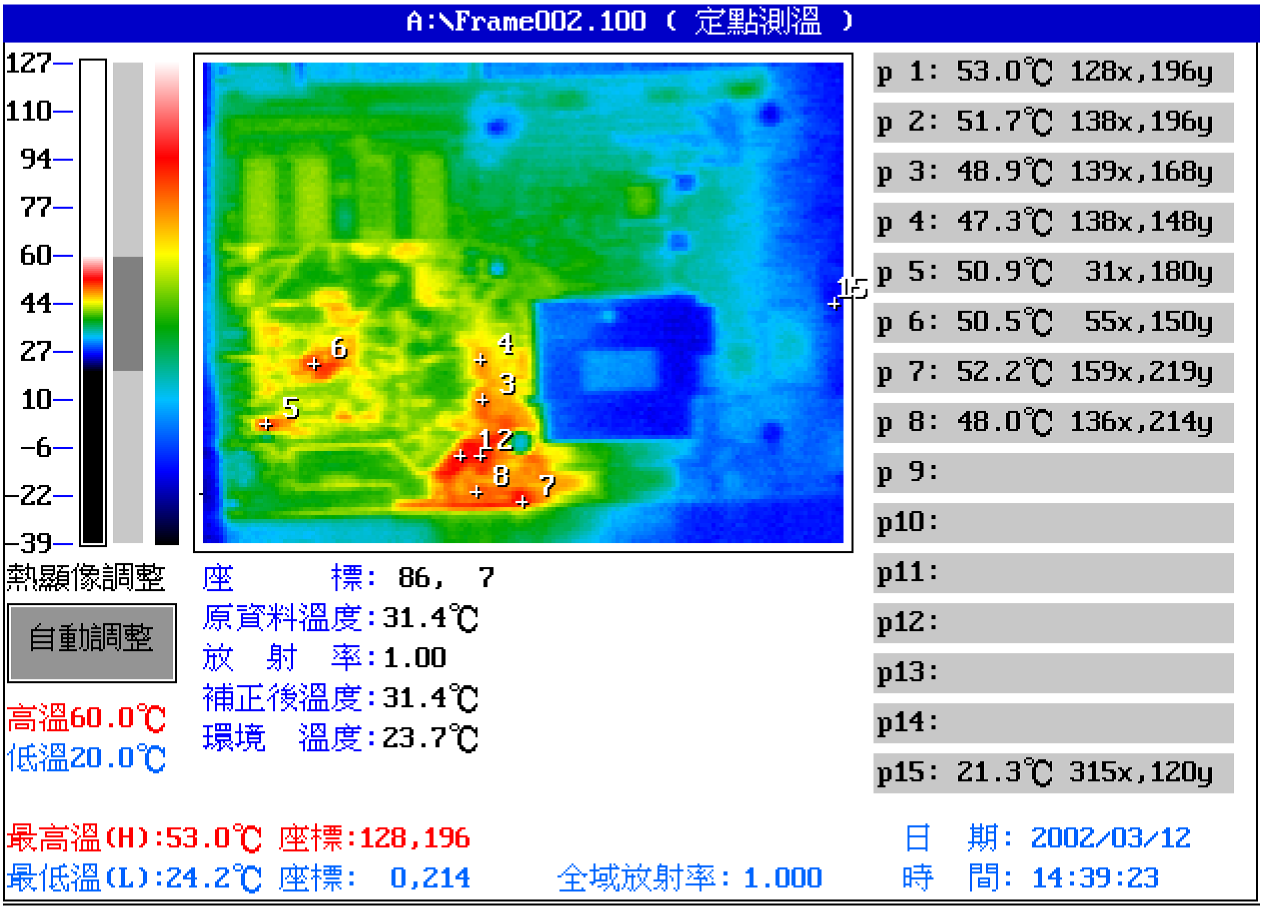
Solder Side:


A:\Frame002.100 (定點測溫)

p 1: 53.0℃ 128x,196y
p 2: 51.7℃ 138x,196y
p 3: 48.9℃ 139x,168y
p 4: 47.3℃ 138x,148y
p 5: 50.9℃ 31x,180y
p 6: 50.5℃ 55x,150y
p 7: 52.2℃ 159x,219y
p 8: 48.0℃ 136x,214y
p 9:
p10:
p11:
p12:
p13:
p14:
p15: 21.3℃ 315x,120y

高溫60.0℃
低溫20.0℃

座 標: 86, 7
原資料溫度:31.4℃
放 射 率:1.00
補正後溫度:31.4℃
環境 溫度:23.7℃

最高溫(H):53.0℃ 座標:128,196
最低溫(L):24.2℃ 座標: 0,214 全域放射率: 1.000

日 期: 2002/03/12
時 間: 14:39:23

Point	Position	Describe	Ts	Tm	Note
1		Open space		53.0℃	
2	C11	TCC. 330uF. 6.3V. 20%. E. SMD		51.7℃	
3	U45	IC. SMD. TEXAS. SN74F32		48.9℃	
4	U44	IC.SMD. SOP. TI. SN74F74DR		47.3℃	
5	Q2	REG.UNISEM.US1010CY		50.9℃	
6		Open space		50.5℃	
7	D6	D. Schottky. PHILIPS. BAT54A		52.2℃	
8		Open space		48.0℃	
15		The Room Temperature		21.3℃	

1. Operation Temperature (℃):
Ts = Defined by component specification ; Tm = Measured by DV
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